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Specifications

Essentials	
Status	End of Interactive Support
Launch Date	Q4'13
Expected Discontinuance	See Roadmap
Board Form Factor	UCFF (4" x 4")
Socket	Soldered-down BGA
Internal Drive Form Factor	mSATA SSD
# of Internal Drives Supported	1
Embedded Options Available	No
Lithography	22 nm
TDP	15 W
DC Input Voltage Supported	12-19 VDC
Recommended Customer Price	N/A
Datasheet	Link
Processor Included	Intel® Core™ i5-4250U Processor (3M Cache, up to 2.60 GHz)
Product Brief	Link
Warranty Period	3 yrs

Memory Specifications	
Max Memory Size (dependent on memory type)	16 GB
Memory Types	DDR3L-1333/1600 1.35V SO-DIMM
Max # of Memory Channels	2
Max Memory Bandwidth	25.6 GB/s
Max # of DIMMs	2
ECC Memory Supported †	No

Graphics Specifications	
Integrated Graphics †	Yes
Graphics Output	Mini-DP 1.2; Mini-HDMI 1.4a
Intel® Clear Video Technology	Yes
# of Displays Supported †	3

Expansion Options	
PCI Express Revision	Gen2
PCI Express Configurations †	Half-length MiniPCI card with PCIe x1 lane
PCIe Mini Card Slot (Half Length)	1
PCIe Mini Card Slot (Full Length)	1

I/O Specifications	
USB Revision	2.0, 3.0
# of USB Ports	6

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PCN/MDDS Information

931577: [PCN](#)
931578: [PCN](#)
931823: [PCN](#)
931824: [PCN](#)

USB 2.0 Configuration (External + Internal)	0 + 2
USB 3.0 Configuration (External + Internal)	2B 2F + 0
Total # of SATA Ports	2
Max # of SATA 6.0 Gb/s Ports	2
Audio (back channel + front channel)	7.1 digital + analog stereo headset
Integrated LAN	10/100/1000
Integrated Wifi	No
Integrated Bluetooth	No
Consumer Infrared Rx Sensor	Yes
Additional Headers	FRONT_PANEL, 2x USB2.0, DC_IN, CUST_SOL (CEC, WDT, DMIC)

Package Specifications

Low Halogen Options Available	See MDDS
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Advanced Technologies

Intel® Virtualization Technology for Directed I/O (VT-d) ‡	Yes
Intel® vPro Technology ‡	No
TPM	No
Intel® HD Audio Technology	Yes
Intel® Rapid Storage Technology	Yes
Intel® Virtualization Technology (VT-x) ‡	Yes

Intel® Data Protection Technology

Intel® AES New Instructions	Yes
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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.


‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

The Recommended Customer –unit purchase quantities, and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. If sold in bulk, price represents individual unit. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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